

ON Semiconductor®

FDB8160-F085 N-Channel PowerTrench® MOSFET

30V, **80A**, **1.8m**Ω

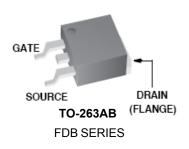
Features

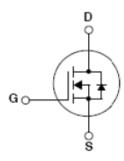
- Typ $r_{DS(on)}$ = 1.5m Ω at V_{GS} = 10V, I_D = 80A
- Typ $Q_{g(10)}$ = 187nC at V_{GS} = 10V
- Low Miller Charge
- Low Qrr Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

Applications

- 12V Automotive Load Control
- Starter/Alternator Systems
- Electronic Power Steering Systems
- DC/DC converter







Units

Max

$\textbf{MOSFET Maximum Ratings} \ \, \text{T_C = 25°C unless otherwise noted}$

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (T _C < 160°C, V _{GS} = 10V)	80	Α
I _D	Pulsed	See Figure 4	^
E _{AS}	Single Pulse Avalanche Energy (Note 1)	1290	mJ
D	Power Dissipation	254	W
P_{D}	Derate above 25°C	1.7	W/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case	0.59	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient TO-263,1in² copper pad area	43	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8160	FDB8160-F085	TO-263AB	330mm	24mm	800 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter

Off Characteristics						
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
		$V_{DO} = 24V \ V_{DO} = 0V$	_	_	1	

Test Conditions

Min

Тур

B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$	-	-	1	μА
DSS	Zero Gate Voltage Drain Current	$T_{J} = 150^{\circ}C$	-	-	250	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
r _{DS(on)} Drain to Source On Resistance	I _D = 80A, V _{GS} = 10V	-	1.5	1.8	mΩ	
	Drain to Source On Resistance	I _D = 80A, V _{GS} = 10V, T _J = 175°C	-	2.6	3.1	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	\/ - 45\/ \/ - 4	V _{DS} = 15V, V _{GS} = 0V,	-	11825	-	pF
C _{oss}	Output Capacitance	$\neg v_{DS} = 15v, v_{GS} = 0$ $\neg f = 1MHz$		-	1810	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112		-	1240	-	pF
Rg	Gate Resistance	f = 1MHz		-	1.75	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		-	187	243	nC
Q _{g(th)}	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	V _{DD} = 15V	-	20	26	nC
Q_{gs}	Gate to Source Gate Charge		I _D = 80A	-	43	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau			-	23	-	nC
Q _{gd}	Gate to Drain "Miller" Charge			-	57	-	nC

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switch	ing Characteristics					

Switching Characteristics

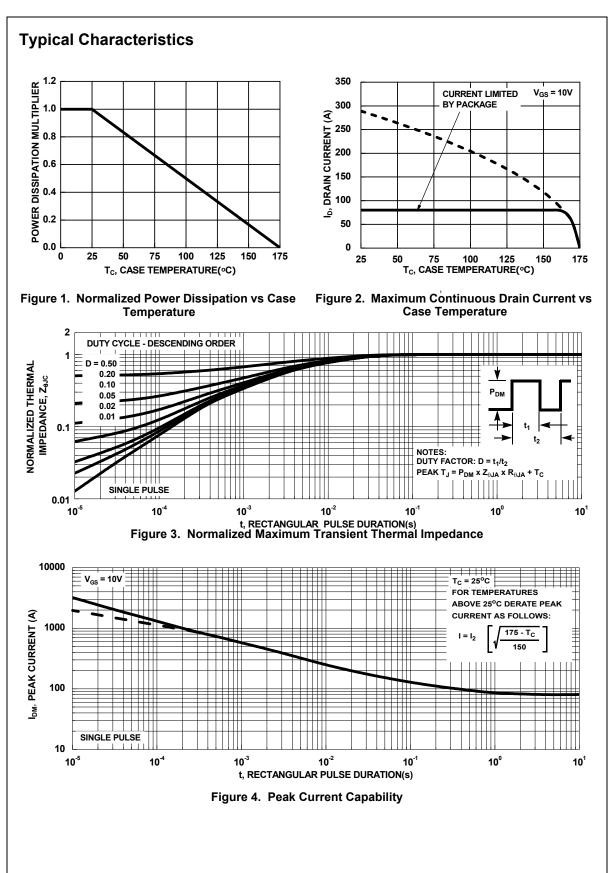
t _{on}	Turn-On Time	V_{DD} = 15V, I_{D} = 80A, V_{GS} = 10V, R_{GS} = 1.3 Ω	-	-	60	ns
t _{d(on)}	Turn-On Delay Time		-	17.2	1	ns
t _r	Turn-On Rise Time		-	18.9	-	ns
t _{d(off)}	Turn-Off Delay Time		-	60	-	ns
t _f	Turn-Off Fall Time		-	27	-	ns
t _{off}	Turn-Off Time		-	-	137	ns

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Voltage	I _{SD} = 80A	-	0.9	1.25	V
		I _{SD} = 40A	-	0.8	1.0	V
t _{rr}	Reverse Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$	-	48	62	ns
Q _{rr}	Reverse Recovery Charge		-	42	55	nC

1: Starting $T_J = 25^{\circ}C$, L = 0.63mH, $I_{AS} = 64$ A **2:** Pulse width = 100s.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All ON Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.



Typical Characteristics

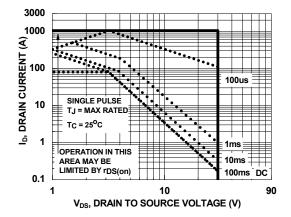
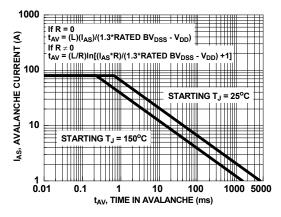


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

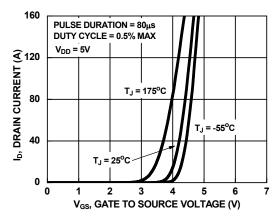


Figure 7. Transfer Characteristics

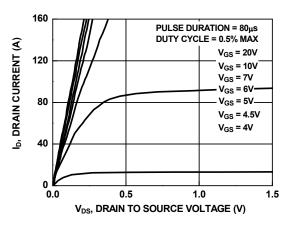


Figure 8. Saturation Characteristics

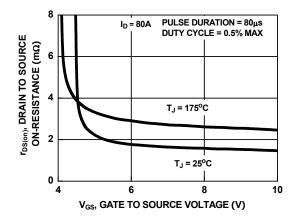


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

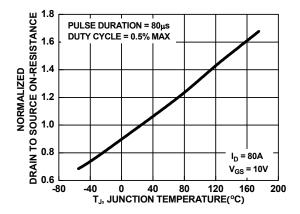


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

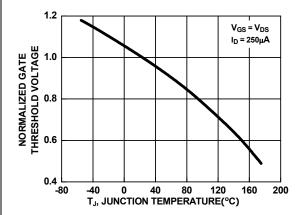


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

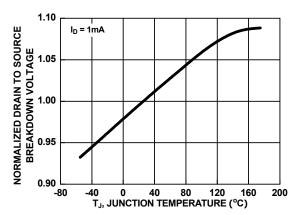


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

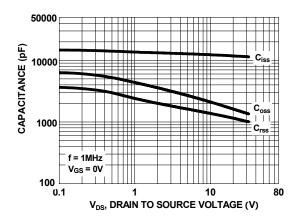


Figure 13. Capacitance vs Drain to Source Voltage

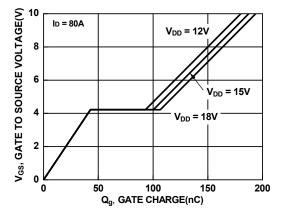


Figure 14. Gate Charge vs Gate to Source Voltage

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